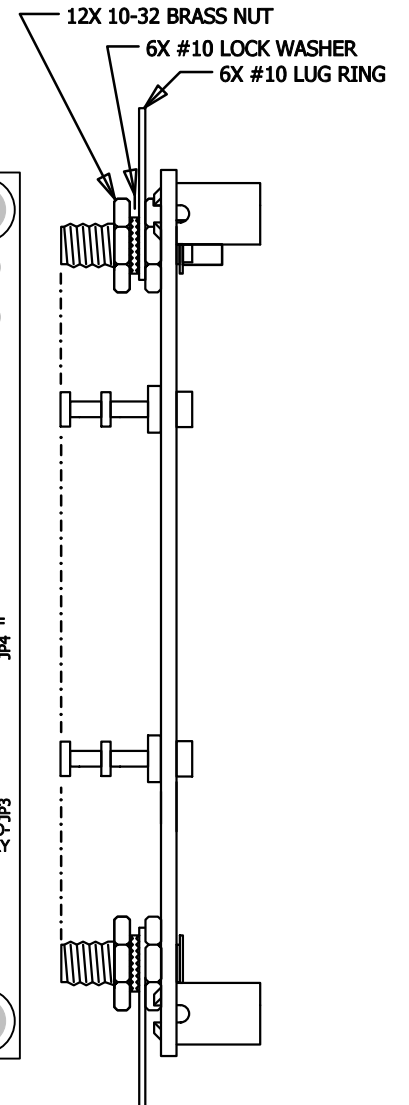
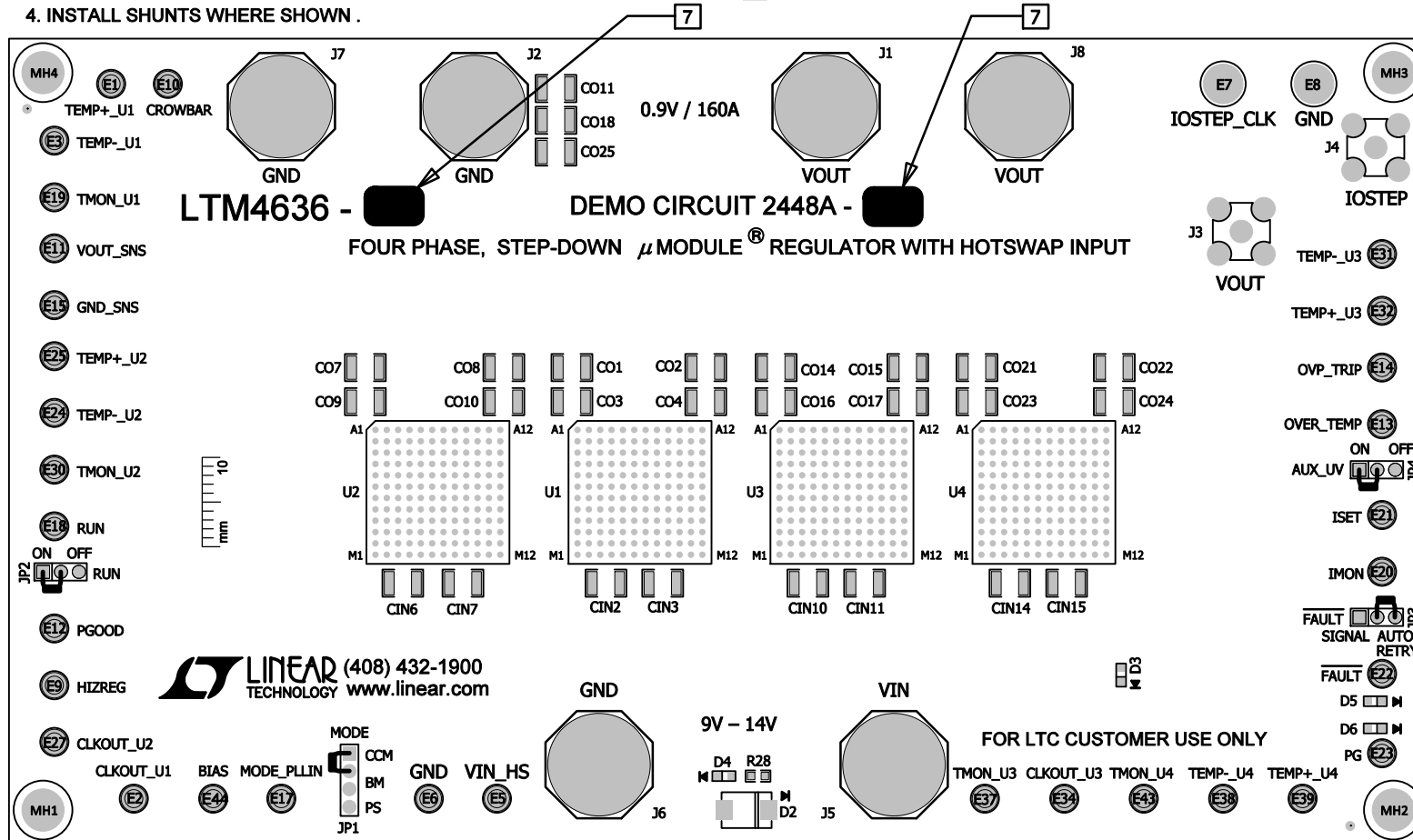


NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS: REFLOW SOLDER TOP SIDE SMD.
MAXIMUM SOLDER TEMPERATURE IS 240 DEG. C.
3. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS WHERE SHOWN .

5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE
BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP
TO ANY BOARD.
7. MARK ASSEMBLY AND IC VERSION WITH PERMANENT MARKER.



LINEAR TECHNOLOGY CORPORATION

DC2448A REV 4

11/21/16

TOP ASSEMBLY

TOP SILKSCREEN

ASSY	IC	IOUT	R16	R17	R56	R65	R71,R73,R74,R75	R11	R25	R76	CIN10-CIN13	CIN14-CIN17	CO19,CO20	CO26,CO27	CO14,CO18	CO21,CO25
-A	U1,U2	80A	0	OPT	OPT	OPT	OPT	OPT	0	0	OPT	OPT	OPT	OPT	OPT	OPT
-B	U1,U2,U3	120A	OPT	0	OPT	OPT	OPT	OPT	0	0	22uF	OPT	470uf	OPT	100uf	OPT
-C	U1,U2,U3,U4	160A	OPT	0	0	0	OPT	OPT	0	0	22uF	22uF	470uf	470uf	100uf	100uf
-D	U1,U2,U3,U4	160A	OPT	0	0	0	66.5k 1%	100k 1%	0.001 1%	OPT	22uF	22uF	470uf	470uf	100uf	100uf